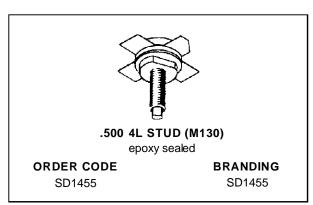
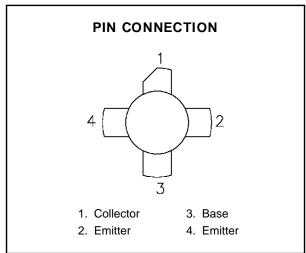


### **SD1455**

# RF & MICROWAVE TRANSISTORS TV/LINEAR APPLICATIONS

- 170 230 MHz
- 25 VOLTS
- IMD 55dB
- COMMON EMITTER
- GOLD METALLIZATION
- HIGH SATURATED POWER CAPABILITY
- DIFFUSED EMITTER BALLAST RESISTORS
- DESIGNED FOR HIGH POWER LINEAR OPERATION
- Pout = 20 W MIN. WITH 8.0 dB GAIN





#### **DESCRIPTION**

The SD1455 is a gold metallized epitaxial silicon NPN planar transistor using diffused emitter ballast resistors for high linearity Class A operation in VHF and Band III television transmitters and transposers.

#### **ABSOLUTE MAXIMUM RATINGS** $(T_{case} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit	
Vceo	Collector-Emitter Voltage	35 V		
V <sub>CES</sub>	Collector-Emitter Voltage	60 V		
V <sub>EBO</sub>	Emitter-Base Voltage	4.0 V		
Ic	Device Current	8.0 A		
Poiss	Power Dissipation	140		
TJ	Junction Temperature	+200 °C		
T <sub>STG</sub>	Storage Temperature	– 65 to +150 °C		

#### THERMAL DATA

R <sub>TH(j-c)</sub> Junction-Case Thermal Resistance	1.5	°C/W
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#### **ELECTRICAL SPECIFICATIONS** (T<sub>case</sub> = 25°C)

#### **STATIC**

Symbol	Test Conditions	Value			Unit		
		Min.	Тур.	Max.			
ВУсво	I <sub>C</sub> = 50 mA	$I_E = 0 \text{ mA}$		65	_	_	V
BV <sub>CER</sub>	I <sub>C</sub> = 50 mA	$R_{BE} = 10 \Omega$		60	_		V
BV <sub>CEO</sub>	I <sub>C</sub> = 50 mA	$I_B = 0 \text{ mA}$		35	_	_	V
BV <sub>EBO</sub>	I <sub>E</sub> = 10 mA	$I_C = 0 \text{ mA}$		4.0	_		V
Ices	V <sub>CE</sub> = 50 V	V <sub>BE</sub> = 0 V		_	_	5	mA
hFE	Vce = 5 V	Ic = 1 A		20	_	120	_

#### **DYNAMIC**

Symbol	Test Conditions			Value			
Syllibol		rest Conditions			Тур.	Max.	Unit
Pout	f = 225 MHz	$V_{CE} = 25 \text{ V}$	$I_{C} = 2.5 A$	20			W
G <sub>P</sub>	f = 225 MHz	$V_{CE} = 25 \text{ V}$	$I_{C} = 2.5 A$	8.0	9.0	_	dB
IMD <sub>3</sub> *	Pout = 14 W	V <sub>CE</sub> = 25 V	I <sub>C</sub> = 2.5 A	_	-55	_	dBc
Сов	f = 1 MHz	Vcb = 30 V		_	_	85	pF

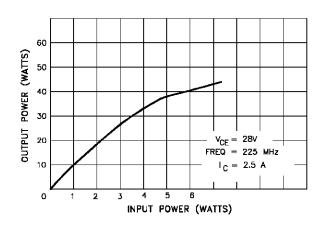
Note: \* f = 225 MHz

3 Tone Testing

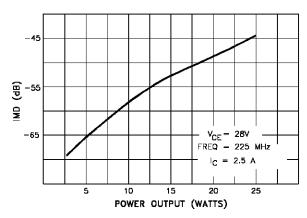
Vision Carrier -8dB/ref Sound Carrier -7dB/ref Sideband Carrier -16dB/ref

#### **TYPICAL PERFORMANCE**

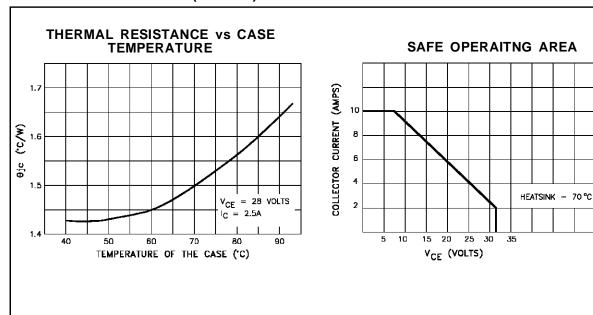
#### **POWER OUTPUT vs POWER INPUT**



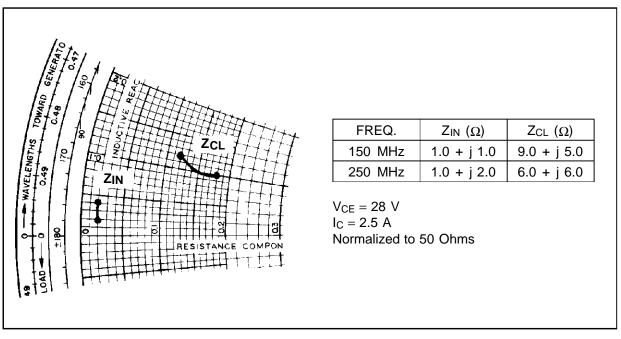
## INTERMODULATION DISTORTION vs POWER OUTPUT



#### TYPICAL PERFORMANCE (CONT'D)



#### **IMPEDANCE DATA**



#### PACKAGE MECHANICAL DATA

	MINIMUM Inches/mm	MAXIMUM Inches/nm	
Α	1.010/25,65	1.050/26,67	
В	.220/5,59	.230/5,84	
С	.495/12,57	.505/12.83	
D	.003/0,08	.007/0,18	
Ε	.160/4,06	180/4,57	
F	.622/15,80		
G	.100/2,54	.130/3,31	
Н	.415/10,54	.425/10,80	
I	.720/18,29		
٦	.250/6,35	.290/7,37	

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